



HUKUSEUU-NI

1U SHORT DEPTH RUGGEDIZED SHIPBOARD SERVER WITH XEON®D-1749NT PROCESSOR (10C), 128GB DDR4 ECC RDIMM, HARDWARE SECURE ERASE (AES)



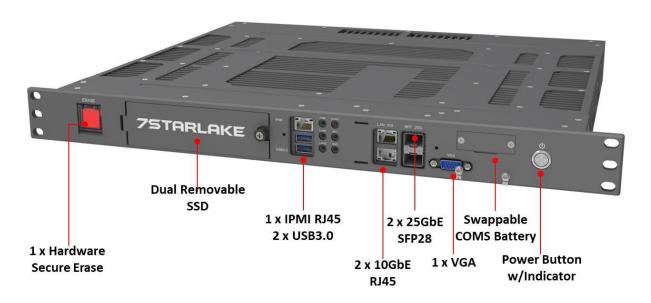




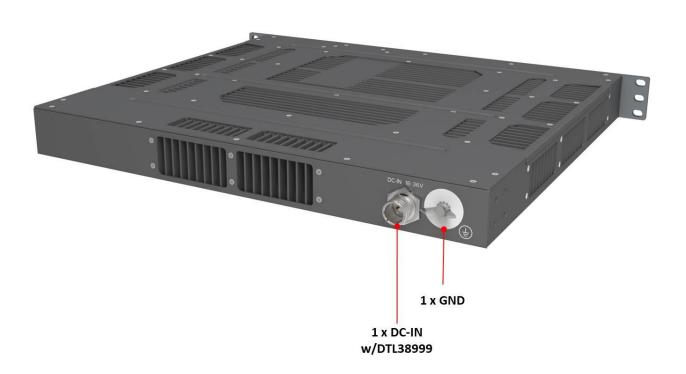
- 1U 380 mm Short Depth Fanless Rugged Server
- MIL-STD 810, MIL-STD 461
- Intel® Xeon® D-1736NT (8xC) / D-1749NT(10xC)
- Up to 128GB Registered ECC RDIMM DDR4-2666MHz
- 2 x 25G SFP28, 2 x 10G RJ45, 1x IPMI
- 1x VGA , 2 x USB 3.0, 1 x GND
- Hardware Secure Erase (AES Key)
- Windows 10/11/Server, Linux, VMware Compatible
- 18~36V DC MIL-461 EMI FILTER Power Supply
- Extreme Temperature -20°C to +60°C

Appearance

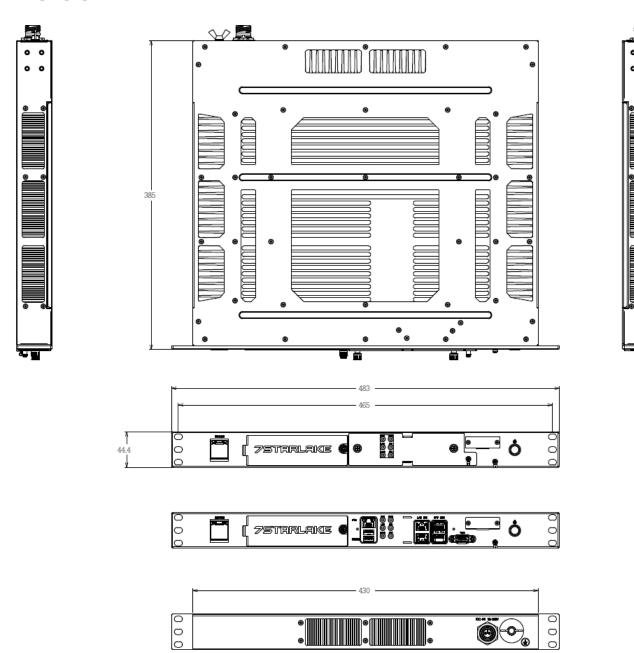
Front I/O



Rear I/O



Dimension



Specifications

SYSTEM

High Performance Processor	Intel® Xeon® D-1736NT (2.7GHz, 8 Cores, 16 Threads, 15MB Cache) Intel® Xeon® D-1749NT (3.0GHz, 10 Cores, 20 Threads, 15MB Cache)
Memory type	Up to 128GB ECC RDIMM, DDR4-2666MT/s
Chipset	SoC, integrated with CPU
IPMI	ASPEED AST2600 BMC
Expansion Slot	1 x PCle x16 (HHHL)
STORAGE	
SDD	2 x 2.5" Swappable SATAIII SSD
ETHERNET	
Ethernet	2 x Intel® SoC 25G SFP28 2 x Intel® X550-AT2 10G RJ45
FRONT I/O	
Button	1 x Secure Erase Button (SSD2 support AES Secure Erase) 1 x Power Switch with Dedicated LED
USB	2 x USB3.0
Ethernet	2 x 25GbE SFP28 2 x 10GbE RJ45 1 x IPMI
Display	1 x VGA
Dedicated LED	2 x SDD LED 4 x Dual Color LED for 8bit GPIO (Reserved)
SSD/HDD Tray	1 x Dual 2.5" SSD Easy Swap Tray
CMOS Battery Tray	1 x Removable CR2032 CMOS Battery Tray
REAR I/O	
DC-IN	1 x DC-IN w/DTL38999
GND	1 x GND
POWER REQUIREMENT	
Power Input	MIL-STD-461, DC-IN 18~36V
OPERATING SYSTEM	

PHYSICAL & ENVIRONMENT

Dimension (W \times D \times H)	430 x 385 x 44.4 mm
Operating Temperature	-20 to 60°C
Storage Temperature	-40 to 85°C
Relative Humidity	5% to 95%, non-condensing
Green Product	RoHS Design to meet
Reliability	No Moving Parts; Passive Cooling. Designed & Manufactured using ISO 9001/2000 Certified Quality Program
MIL-STD-810	MILS-STD-810 Design to meet: Method 501, Operational Temperature, high / Procedure II: +50°C, two-hour dwell, four cycles Method 501, Storage Temperature, high / Procedure I: +70°C, two-hour dwell, four cycles Method 502, Operational Temperature, low / Procedure II: -20°C, two-hour dwell, four cycles Method 502, Storage Temperature, low / Procedure I: -40°C, two-hour dwell, four cycles Method 514, Vibration / Category 24/Non-Operating (Category 20 & 24, Vibration) Method 514, Vibration / Category 20/Operating (Category 20 & 24, Vibration) Method 516, Shock / Procedure V Non-Operating (Mechanical Shock) Method 516, Shock / Procedure I Operating (Mechanical Shock)
EMC	MIL-STD-461 Design to meet :

CE102-Conducted emissions, power leads, 10KHz to 10MHz

RE102-Radiated emissions, electric filed, 30MHz to 5GHz

RS103-Radiated susceptibility, electric filed, 80MHz to 3GHz

EN 61000-4-2: Air discharge: 8 kV, Contact discharge: 6kV

EN 61000-4-3: 10V/m

EN 61000-4-4: Signal and DC-Net: 1 kV

EN 61000-4-5: Leads vs. ground potential 1kV, Signal und DC-Net: 0.5 kV

EN 55022, Class A

CE and FCC

Ordering Information

HORUS200-X1-8C

1U Short Depth Ruggedized Shipboard Server with Intel® Xeon® D-1736NT(8C) (TDP: 67W) Processor, Up to 128GB ECC RDIMM, DDR4-2666MT/s, 1 x IPMI, 4 x Ethernet, 1 x VGA, 2 x USB, 2 x Removable SSD, 1 x Removable CMOS Battery, Secure Erase Button, $18\sim36$ V DC-IN w/DTL38999, Operating Temp. - $20\sim60$ °C

HORUS200-X1-10C

1U Short Depth Ruggedized Shipboard Server with Intel® Xeon® D-1749NT(10C) (TDP:90W) Processor, Up to 128GB ECC RDIMM, DDR4-2666MT/s, 1 x IPMI, 4 x Ethernet, 1 x VGA, 2 x USB, 2 x Removable SSD, 1 x Removable CMOS Battery, Secure Erase Button,18~36V DC-IN w/DTL38999, Operating Temp. - 20~60°C

This datasheet is for marketing purposes only and does not constitute a warranty. All specifications, dimensions, and data are subject to change without notice. For the latest specifications and updates, please contact your 7STARLAKE representatives.